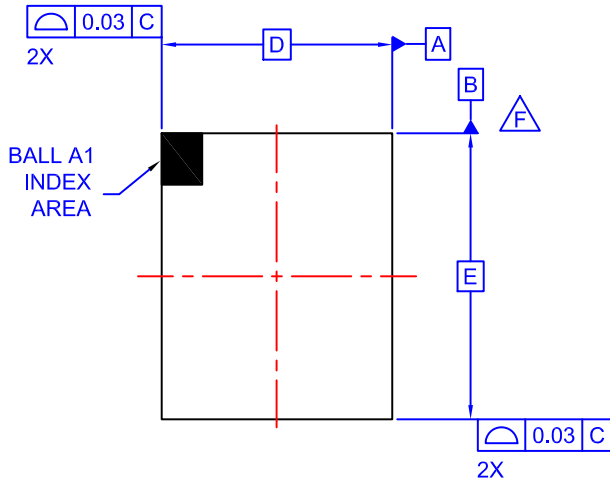


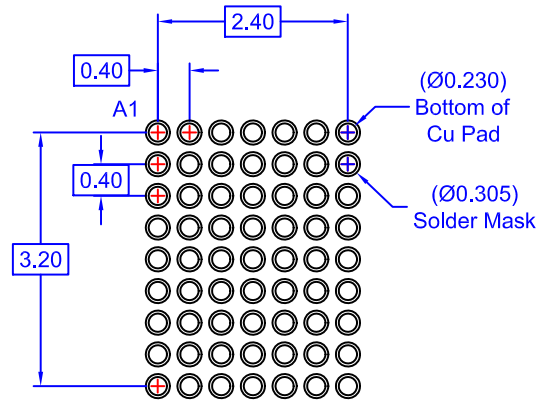


WLCSP63 3.63x2.83x0.522
CASE 567TM
ISSUE O

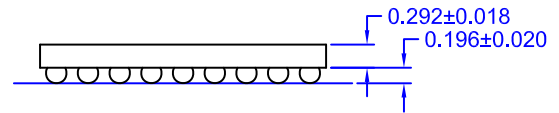
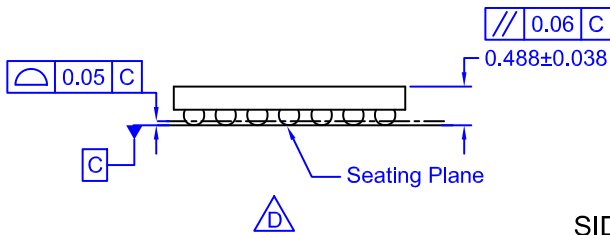
DATE 31 MAR 2017



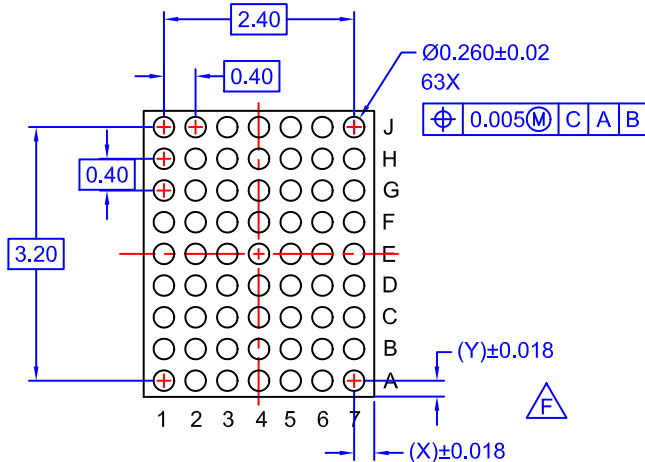
TOP VIEW



RECOMMENDED LAND PATTERN
(NSMD TYPE)



SIDE VIEWS



BOTTOM VIEW

NOTES

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASMEY14.5M, 2009.

- D.** DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E.** PACKAGE NOMINAL HEIGHT IS 488 ± 38 MICRONS (450-526 MICRONS).
- F.** FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	WLCSP63 3.63x2.83x0.522	PAGE 1 OF 1

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